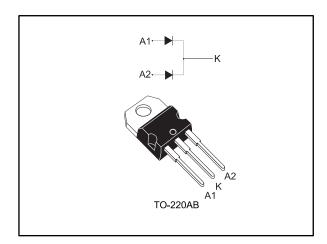
STPS60170C



High voltage power Schottky rectifier

Datasheet - production data



Features

- High junction temperature capability
- Good trade-off between leakage current and forward voltage drop
- Low leakage current
- Low thermal resistance
- Avalanche capability specified
- High frequency operation
- ECOPACK®2 compliant component

Description

This dual diode Schottky rectifier is suited for high frequency switched mode power supplies.

Packaged in TO-220AB this device is intended for use to enhance the reliability of the application.

Table 1: Device summary

Symbol	Value
I _{F(AV)}	2 x 30 A
V_{RRM}	170 V
T _j (max.)	175 °C
V _F (typ.)	0.76 V

Characteristics STPS60170C

1 Characteristics

Table 2: Absolute ratings (limiting values, per diode, at 25 °C, unless otherwise specified)

Symbol	Paramete	Value	Unit			
V_{RRM}	Repetitive peak reverse voltage			170	٧	
I _{F(RMS)}	Forward rms current			45	Α	
1	Average forward current $\delta = 0.5$, T 450.00 Pe		Per diode	30	^	
I _{F(AV)}	square wave	T _C = 150 °C	Per device	60	Α	
I _{FSM}	Surge non repetitive forward current $t_p = 10 \text{ ms}$ sinusoidal			270	Α	
P _{ARM}	Repetitive peak avalanche power $ \begin{array}{c} t_p = 10 \; \mu s, \\ T_j = 125 \; ^{\circ} C \end{array} $			985	W	
T _{stg}	Storage temperature range			-65 to +175	°C	
Tj	Maximum operating junction temperature (1)			175	C	

Notes:

Table 3: Thermal parameters

Symbol	Parameter Ma			Unit
D	lunction to coop	Per diode	1.0	
R _{th(j-c)} Junction to case	Junction to case	Total	0.7	°C/W
R _{th(c)}	Coupling		0.4	

When the diodes 1 and 2 are used simultaneously:

 $\Delta T_{j\;(diode1)} = P_{(diode1)}\;x\;R_{th(j\text{-}c)}\;(per\;diode) + P_{(diode2)}\;x\;R_{th(c)}$

Table 4: Static electrical characteristics (per diode)

Symbol	Parameter	Test conditions		Min.	Тур.	Max.	Unit
I _R ⁽¹⁾	Poverse leekage ourrent	T _j = 25 °C	V _R = V _{RRM}	1		35	μΑ
IR ^(*)	Reverse leakage current	T _j = 125 °C	VR = VRRM	1	8	35	mA
	$V_{F}^{(2)} \qquad \text{Forward voltage drop} \qquad \begin{array}{c} T_{j} = 25 \ ^{\circ}\text{C} \\ \hline T_{j} = 125 \ ^{\circ}\text{C} \\ \hline T_{j} = 25 \ ^{\circ}\text{C} \\ \hline T_{j} = 125 \ ^{\circ}\text{C} \\ \end{array} \qquad \text{I}_{F} = 30 \ \text{A}$	-		0.94			
V (2)		T _j = 125 °C	IF = 30 A	-	0.72	0.76	V
VF(=)		T _j = 25 °C	I _F = 60 A	-	0.97	1.05	V
		T _j = 125 °C			0.86	0.92	

Notes:

 $^{(1)} Pulse$ test: tp = 5 ms, δ < 2%

 $^{(2)}$ Pulse test: t_p = 380 µs, δ < 2%

To evaluate the conduction losses, use the following equation:

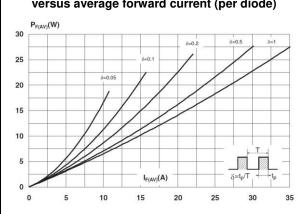
 $P = 0.60 \ x \ I_{F(AV)} + 0.0053 \ x \ I_{F^2(RMS)}$

 $^{^{(1)}(}dP_{tot}/dT_j) < (1/R_{th(j\text{-}a)}) \ condition \ to \ avoid \ thermal \ runaway \ for \ a \ diode \ on \ its \ own \ heatsink.$

STPS60170C Characteristics

1.1 Characteristics (curves)

Figure 1: Average forward power dissipation versus average forward current (per diode)



temperature (δ = 0.5, per diode)

I_{F(AV)}(A)

35

30

25

20

15

R_{poper}15°C/W

Figure 2: Average forward current versus ambient

Figure 3: Normalized avalanche power derating versus pulse duration (Tj = 125 °C)

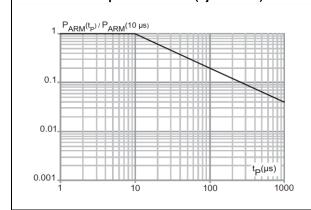


Figure 4: Relative variation of thermal impedance junction to case versus pulse duration

100

125

150

175

25

0

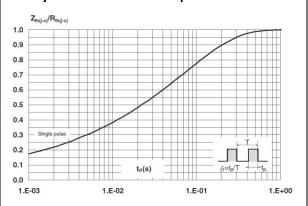


Figure 5: Reverse leakage current versus reverse voltage applied (typical values, per diode)

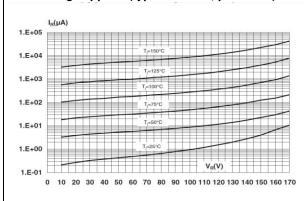
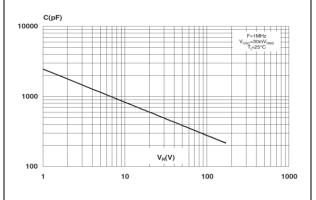


Figure 6: Junction capacitance versus reverse voltage applied (typical values, per diode)



Characteristics STPS60170C

Figure 7: Forward voltage drop versus forward current (per diode, low level)

1_{FM}(A)
30
25
T_{J=125°C}
(Maximum values)
10
5
V_{FM}(V)
0.0 0.1 0.2 0.3 0.4 0.5 0.6 0.7 0.8 0.9 1.0

Figure 8: Forward voltage drop versus forward current (per diode, high level)

IFM (A)

1000

IFM (A)

1000

IFM (A)

IF

STPS60170C Package information

2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: **www.st.com**. ECOPACK® is an ST trademark.

• Cooling method: by conduction (C)

• Epoxy meets UL 94,V0

Recommended torque value: 0.55 N·m

• Maximum torque value: 0.7 N·m

2.1 TO-220AB package information

Figure 9: TO-220AB package outline øΡ H1 D D1 L20 L30 b1(X3) - b (X3) _e 1_

47/

Table 5: TO-220AB package mechanical data

	Dimensions				
Ref.	Millimeters		Inc	ches	
	Min.	Max.	Min.	Max.	
Α	4.40	4.60	0.173	0.181	
b	0.61	0.88	0.240	0.035	
b1	1.14	1.70	0.045	0.067	
С	0.48	0.70	0.019	0.028	
D	15.25	15.75	0.600	0.620	
D1	1.27	typ.	0.050	0 typ.	
E	10.00	10.40	0.394	0.409	
е	2.40	2.70	0.094	0.106	
e1	4.95	5.15	0.195	0.203	
F	1.23	1.32	0.048	0.052	
H1	6.20	6.60	0.244	0.260	
J1	2.40	2.72	0.094	0.107	
L	13.00	14.00	0.512	0.551	
L1	3.50	3.93	0.138	0.155	
L20	16.40 typ.		0.640	6 typ.	
L30	28.90 typ.		1.138	8 typ.	
θР	3.75	3.85	0.148	0.152	
Q	2.65	2.95	0.104	0.116	

STPS60170C Ordering information

3 Ordering information

Table 6: Ordering information

Order code	Marking	Package	Weight	Base qty.	Delivery mode
STPS60170CT	STPS60170CT	TO-220AB	1.95 g	50	Tube

4 Revision history

Table 7: Document revision history

Date	Revision	Changes
18-Feb-2005	1	First issue.
11-Dec-2015	2	Updated conduction losses equation values and reformatted to current standard.
15-Jan-2018	3	Updated Table 2: "Absolute ratings (limiting values, per diode, at 25 °C, unless otherwise specified)".

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